



VDRM

T(AV)

Iтѕм dV/dt*

dl/dt

KEY PARAMETERS

4200V

4160A

56100A

2000V/µs

500A/µs

* Higher dV/dt selections are available on request

DCR4160A42

Replaces DS6362-1

Phase Control Thyristor

DS6362-2	March 2022	(LN41638)
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FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- Bridge Rectifiers
- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages VDRM and VRRM (V)	Conditions
DCR4160A42* DCR4160A40 DCR4160A36	4200 4000 3600	$T_{vj} = -40^{\circ}C \text{ to } 125^{\circ}C,$ IDRM = IRRM = 300MA, $VDRM, VRRM t_P = 10ms$ VDSM & VRSM = VDRM & VRRM + 100V respectively

Lower voltage grades available.

*4100V @ -40°C, 4200V @ 0°C

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR4160A42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

Outline type code: A (See Package Details for further information)

Fig. 1 Package outline

CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
Ιτ(Αν)	Mean on-state current	Half wave resistive load	4160	А
It(rms)	RMS value	-	6530	А
Іт	Continuous (direct) on-state current	-	5840	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	56.1	kA
l²t	I ² t for fusing	VR = 0	15.7	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditior	Min.	Max.	Units	
	Rth(j-c) Thermal resistance - junction to case	Double side cooled	DC	-	6.0	°C/kW
Rth(j-c)			Anode DC	-	10.4	°C/kW
		Single side cooled	Cathode DC	-	14.9	°C/kW
Back	Thermal registeres access to heateink	Clamping force 83kN (with mounting compound)	Double side	-	1.0	°C/kW
Ktn(c−n)	Rth(c-h) Thermal resistance - case to heatsink		Single side	-	2.0	°C/kW
Tvj	Virtual junction temperature	Blocking Vdrm / Vrrm		-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			74	91	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditior	IS	Тур.	Max.	Units
I	Deals assess and aff state assess	At Vrrm/Vdrm, Tcase = 125°C		-	300	mA
Irrm/Idrm	Peak reverse and off-state current	At 50% VRRM/VDRM, Tcase = 7	125°C	20	-	mA
Symbol	Parameter	Test Conditior	IS	Min.	Max.	Units
Vтм	Instantaneous forward voltage	At 4000A peak, Tj = 125°C		1.45	1.60	V
dV/dt	Max. linear rate of rise of off-state voltage	То 67% V _{DRM} , Тј = 125°С, g	ate open	-	2000	V/µs
dl/dt	Rate of rise of on-state current	From 67% VDRM to 2x IT(AV) Gate source 30V, 10Ω	Repetitive 50Hz	-	200	A/µs
dijat		tr < 0.5µs, Tj = 125°C	Non-repetitive	-	500	A/µs
	Threshold voltage - Low level	500A to 3200A at Tcase = 125°C		-	0.89	V
V τ(το)	Threshold voltage - High level	3200A to 9000A at T _{case} = 125°C		-	1.08	V
-	On-state slope resistance - Low level	500A to 3200A at T _{case} = 125°C		-	0.19	mΩ
Гт	On-state slope resistance - High level	3200A to 9000A at Tcase = 125°C		-	0.13	mΩ
tgd	Delay time	$V_D = 67\% V_{DRM}$, gate source 30V, 10 Ω tr = 0.5µs, Tj = 25°C		-	3	μs
tq	Turn-off time	IT = 5000A, Tj = 125°C, VR = 200V, dl/dt = 5A/µs, dVpR/dt = 20V/µs linear		-	900	μs
Qs	Stored charge	I⊤ = 1700A, Tj = 125°C, dl/dt = 1A/µs,		1570	2570	μC
Irr	Reverse recovery current	VR ~ 1700V, Cs = 1μF, Rs = 63Ω		33	42	А
IL.	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	А
Ін	Holding current	Тј = 25°С, R _{G-} к = ∞, Iтм = 50	0A, I⊤ = 5A	-	300	mA

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GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Vgт	Gate trigger voltage	Vdrм = 5V, Tcase = 25°С	1.5	V
Vgd	Gate non-trigger voltage	At 50% Vdrm, Tcase = 125°C	0.4	V
Іст	Gate trigger current	Vdrм = 5V, Tcase = 25°С	400	mA
Igd	Gate non-trigger current	At 50% Vdrм, Tcase = 125°С	10	mA

CURVES

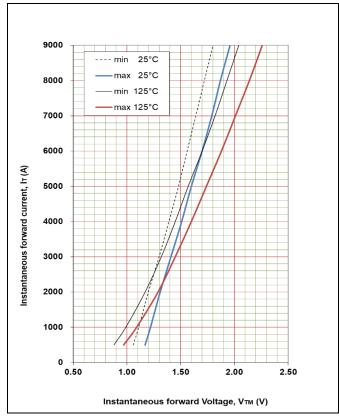


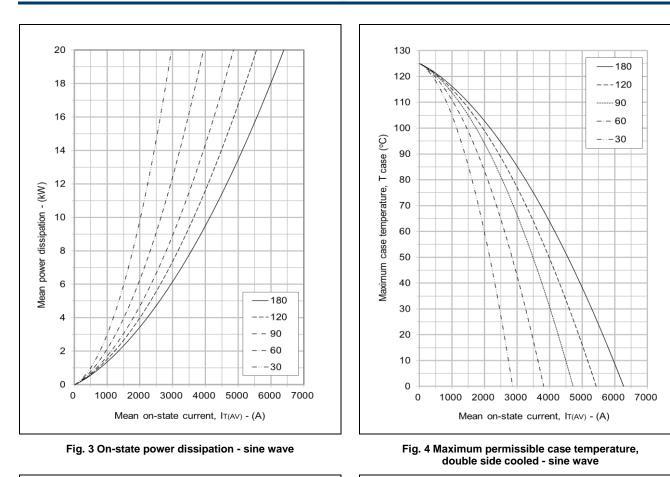
Fig. 2 Maximum & minimum on-state characteristics

VTM EQUATION

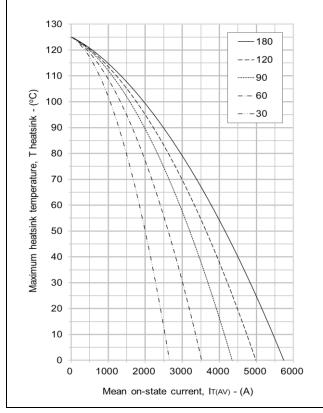
 $V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$

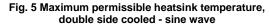
Where A = -0.157228 B = 0.182115 C = 0.000133 D = -0.004511 These values are valid for $T_j = 125^{\circ}C$ for IT 500A to 9000A

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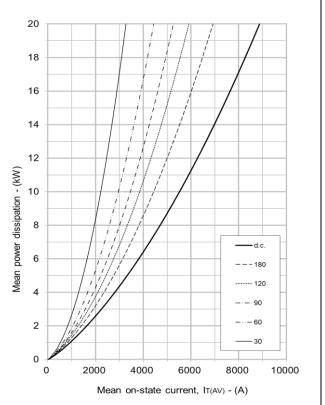


Fig. 6 On-state power dissipation - rectangular wave

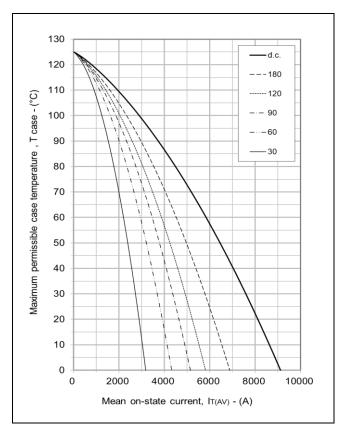
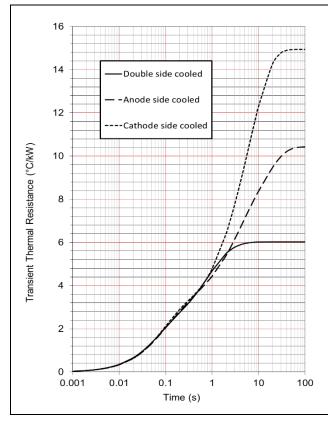


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



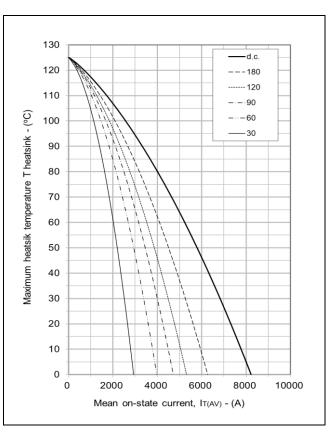


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	3.015	1.049	0.984	0.984
cooled	Ti(s)	0.704	1.905	0.059	0.059
Anode side cooled	Ri(°C/kW)	3.156	4.093	1.557	1.624
	Ti(s)	2.690	13.792	0.059	0.206
Cathode side	Ri(°C/kW)	7.077	3.483	1.746	2.634
cooled	Ti(s)	6.649	8.436	1.762	0.081

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

 $\Delta R_{th(j-c)}$ Conduction

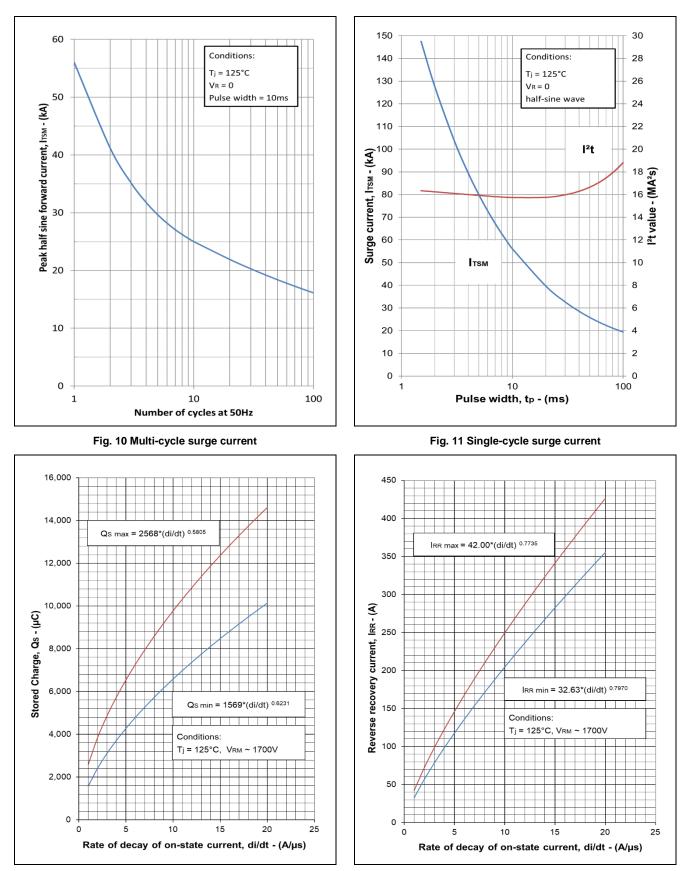
Tables show the increments of thermal resistance R $_{\text{frij-ej}}$ when the device operates at conduction angles other than d.c.

D	ouble side c	ooling	A	Anode Side Cooling			Cath	ode Side	ed Cooling		
	ΔZ_{th}	(z)		$\Delta Z_{\text{th}}(z)$		$\Delta Z_{th}(z)$				ΔZ	_{th} (z)
θ°	sine.	rect.	θ°	sine.	rect.	I I	θ°	sine.	rect.		
180	0.44	0.31	180	0.42	0.30	1	80	0.42	0.30		
120	0.49	0.43	120	0.47	0.41	1	20	0.47	0.41		
90	0.55	0.49	90	0.52	0.46		90	0.52	0.46		
60	0.60	0.55	60	0.57	0.52		60	0.57	0.52		
30	0.64	0.61	30	0.61	0.58		30	0.60	0.58		
15	0.66	0.64	15	0.62	0.61		15	0.62	0.60		

Fig.9 Maximum (limit) transient thermal impedance – junction to case (degC/kW)

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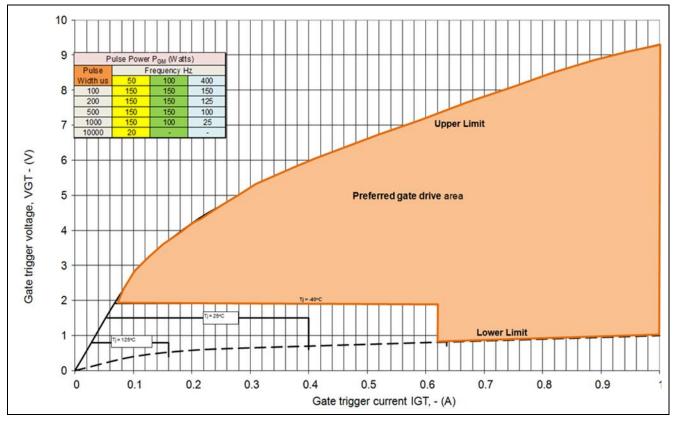
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Fig. 12 Stored charge

Fig. 13 Reverse recovery current



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Fig.14 Gate characteristics

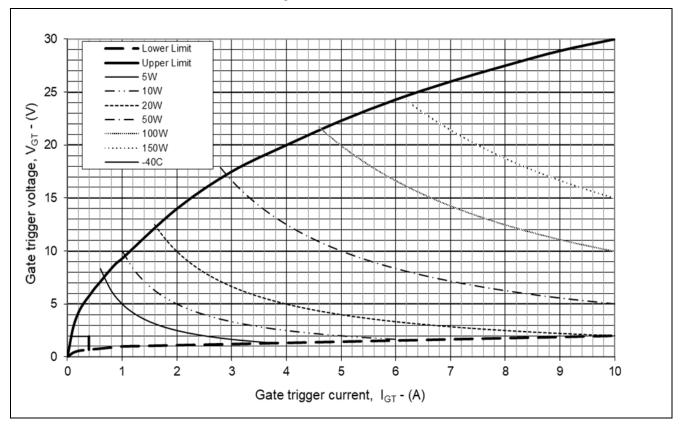


Fig. 15 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE

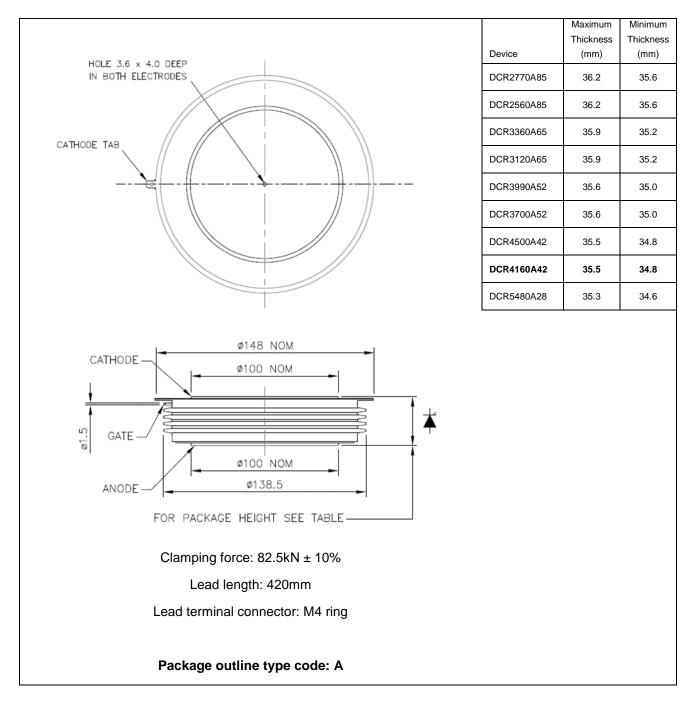


Fig. 16 Package outline

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